

IPC/JEDEC J-STD-609B

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Supersedes IPC/JEDEC J-STD-609A

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JOINT INDUSTRY STANDARD

Marking and Labeling
of Components,
PCBs and PCBAs to
Identify Lead (Pb),
Lead-Free (Pb-Free)
and Other Attributes

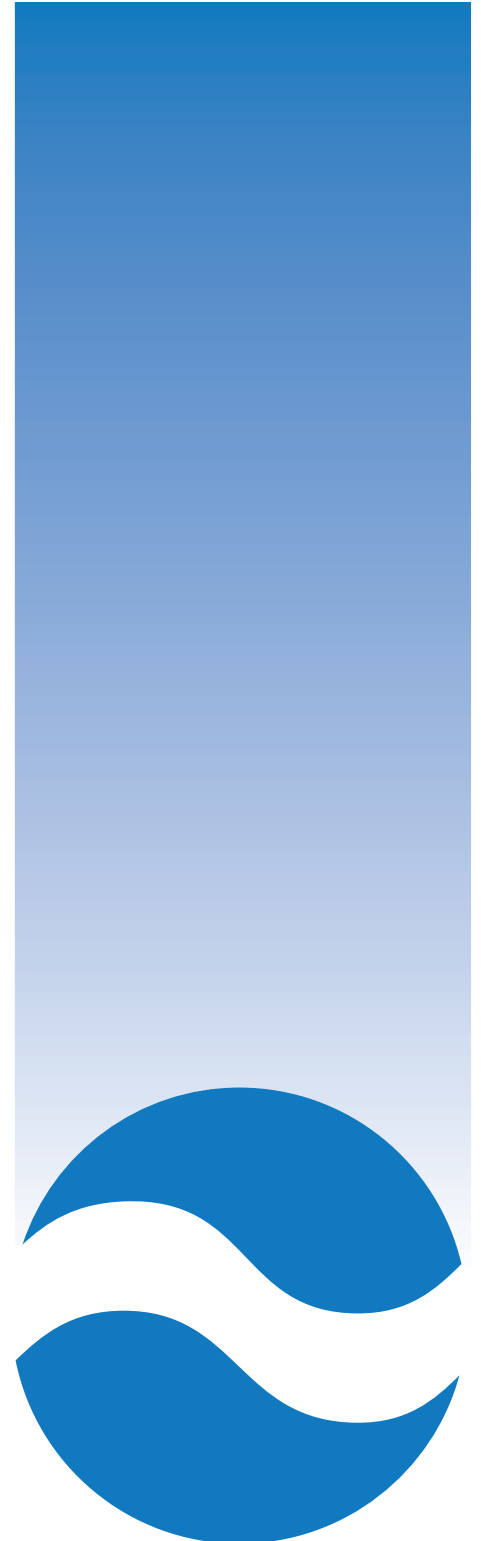


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